Compliant with IEC 62474/ D9.00 Compliant to IEC 61249-2-21:2003

Semiconductor Device Type:	24 QFN 5x5x0.9mm Matte Tin	Termination Base Alloy: Copper Alloy (Cu)			Package Homogeneous Materials				J-STD-609A Product Marking and/or Pkg. Labeling e3	
Basic Substance	CAS Number	"Contained In" Sub-Component	% Total Weight	mg/part	ppm	33.85	(mg) Total	Mold Compound	% ot Total Weight	48.78
Silica, fused	60676-86-0	Mold Compound	43.902	30,468	439.020	1	Silica, fused	60676-86-0	90.00	
Epoxy Resin	500-033-5	Mold Compound	2.366	1.642	23,658		Epoxy Resin	500-033-5	4.85	
Phenolic Resin	Trade Secret	Mold Compound	2.366	1.642	23,658		Phenolic Resin	Trade Secret	4.85	
Carbon Black	1333-86-4	Mold Compound	0.146	0.102	1,463		Carbon Black	1333-86-4	0.30	
Copper	7440-50-8	Lead Frame	36.476	25.314	364.762	L		Total	100.00	
Iron	7439-89-6	Lead Frame	0.897	0.623	8.972	26.50	(mg) Total	Lead Frame	% of Total Weight	38.18
Silver	7440-22-4	Lead Frame	0.727	0.505	7,273	1	Copper	7440-50-8	95.54	
Zinc	7440-66-6	Lead Frame	0.048	0.033	477		Iron	7439-89-6	2.35	
Phosphorous	7723-14-0	Lead Frame	0.031	0.022	315		Silver	7440-22-4	1.91	
Silver	7440-22-4	Die Attach	0.930	0.645	9.300		Zinc	7440-66-6	0.13	
Epoxy resin	68475-94-5	Die Attach	0.260	0.181	2,604		Phosphorous	7723-14-0	0.08	
Copper(II) oxide	1317-38-0	Die Attach	0.050	0.034	496	ų		Total	100.00	
Silicon	7440-21-3	Dual Chip (Die)	6.770	4.698	67,700	0.86	(mg) Total	Die Attach	% of Total Weight	1.24
Copper	7440-50-8	Wire Bond Copper palladium coated (CuPd)	0.737	0.511	7.369		Silver	7440-22-4	75.00	
Palladium	7440-05-3	Wire Bond Copper palladium coated (CuPd)	0.013	0.009	131		Epoxy resin	68475-94-5	21.00	
Tin	7440-31-5	Plating on external leads (pins) - Matte Tin / annealed at 150°C for 1 hour	4.280	2.970	42,800		Copper(II) oxide	1317-38-0	4.00	
		TOTALS:	100.000	69.400	1.000.000	u		Total	100.00	
	0.0604	g Total Mass			.,,	4.70	Total (mg)	Dual Chip (Die)	% of Total Weight	6.77
) and 2000/53/EC and 2016/774/EU (End-of-Life Vehicles (ELV) without exemption (zero) pliance with the above EU Directives has been verified via internal design controls, supplier declarations, and /or analytical test data. themical substance is absent from the list above, the chemical substance is NOT an intentional ingredient in the semiconductor device and, to the best of Microchip Technology					J (31 March		Doped Silicon	7440-21-3	100	
pliance with the above EU Directives has been verified via interi	nal design contro	ols, supplier declarations, and /or analytical test data.			•		Doped Silicon	7440-21-3 Total	100	
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liance with the above EU Directives has been verified via interi emical substance is absent from the list above, the chemical s porated's knowledge and belief as of the date of this document is not below the threshold of regulatory concern for any regulat ng compounds used by Microchip meet the UL94 V0 flammabil ul.com/global/eng/pages/offerings/industries/chemicals/plastic	nal design contro ubstance is NOT , there is no cred ory scheme worl lity standard for p	Is, supplier declarations, and /or analytical test data. an intentional ingredient in the semiconductor device and ible reason to believe that the unavoidable impurity conce d-wide. olastics. You can access the UL iQTM family of databases t	ntration of the	Microchip Tec chemical subs	chnology stance, if	0.52		Total Wire Bond Copper palladium	100.00	0.75
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